

Encapsulating or sealing microelectronic hybrid semiconductor circuits

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Abstract of DE4434382

Hybrid modules with a series of connecting wires and unencapsulated semiconductors on a substrate, having a two-sided adhesive tape or thermoplastic adhesive tape, are applied to a support material to form an edge border to restrict the flow of an encapsulating thermal or UV-curable potting material or other plastic layer. The tape is used as a fixer in further assembly steps.

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